

[10191/1614]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Richard SPITZ et al.
Serial No. : To Be Assigned
Filed : Herewith
For : METHOD FOR ELIMINATING DEFECTS IN SILICON
ELEMENTS THROUGH SELECTIVE ETCHING
Art Unit : To Be Assigned
Examiner : To Be Assigned

Assistant Commissioner
for Patents
Washington, D C 20231

PRELIMINARY AMENDMENT

SIR:

Please amend the above-identified application before examination, as set forth below.

IN THE SPECIFICATION:

Page 1, before line 1, insert:

--FIELD OF THE INVENTION--.

Page 1, line 4, change "wafer according to the" to --wafer:--.

Page 1, delete line 5.

Page 1, delete line 7.

Page 1, before line 9, insert:

--BACKGROUND INFORMATION--.